



# 100% Material Declaration Data Sheet CS48

PK148 (v1.2) September 28, 2006

Material Declaration Data Sheet

**Average Weight: 0.2 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.00562</b>	<b>2.81%</b>
	Silicon	7440-21-3	100.00		0.00562	
<b>Die Attach Material</b>					<b>0.0018</b>	<b>0.59%</b>
	Silver	7440-22-4	78.00		0.001404	
	Resin (EP)	Trade Secret	22.00		0.000396	
<b>Encapsulant</b>					<b>0.0947</b>	<b>47.35%</b>
	Epoxy Resins	Trade Secret	6.00		0.005682	
	Phenolic Resins	Trade Secret	6.00		0.005682	
	Carbon Black	1333-86-4	0.50		0.0004735	
	SiO2 Filler	60676-86-0	84.00		0.079548	
	Bismuth	7440-69-9	Max 1.00		0.000947	
	Metal Hydroxide	Trade Secret	2.50		0.0023675	
<b>Laminate</b>					<b>0.0301</b>	<b>15.05%</b>
	Bismaleimide/Triazine Board	13676-54-5 / 25722-66-1	72.685		0.021878185	
	Copper	7440-50-8	9.880		0.00297388	
	Nickel	7440-02-0	7.270		0.00218827	
	Gold	7440-57-5	1.160		0.00034916	
	Antimony Pentoxide	1314-60-9	0.005		0.000001505	
	Brominated Resin	68541-56-0	9.000		0.002709	
<b>Bond Wire</b>					<b>0.00036</b>	<b>0.18%</b>
	Gold	7440-57-5	100.00		0.00036	
<b>Solder Balls</b>					<b>0.06804</b>	<b>34.02%</b>
	Tin	7440-31-5	63.00		0.0428652	
	Lead	7439-92-1	37.00		0.0251748	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
4/06/06	1.0	Initial release.
7/21/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions and weights.